

3.2x1.0 x1.5mm Side View Chip LED

OSXX1204C1E

■Features

- · Single chip
- · Super high brightness of surface mount LED
- Compact package outline
 (L x W x T) of 3.2mm x 1.0mm x1.5mm
- · Compatible to IR reflow soldering.

■Applications

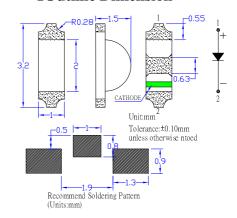
- Backlighting (switches, keys, etc.)
- Marker lights (e.g. steps, exit ways, etc.)

■Absolute Maximum Rating

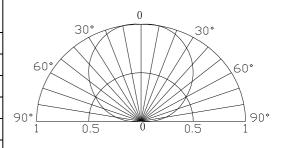
(Ta=25°C)

Value Item Symbol Unit WA/M5/K4/B5/G5 G8/Y5/O5/R5 DC Forward Current I_F 30 25 mΑ Pulse Forward Current* 80 100 I_{FP} mA Reverse Voltage V_R 5 5 V Power Dissipation 102 mW P_{D} $^{\circ}$ C -40 ~ +85 Operating Temperature Topr $^{\circ}$ C Storage Temperature Tstg -40~ +85 260°C/10sec Lead Soldering Temperature Tsol

■Outline Dimension



Directivity



■Electrical -Optical Characteristics

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		$V_{F}(V)$		$I_R(\mu A)$	I	v(mcd)			λD(nm)		2θ1/2	2θ1/2(deg)			
Part Number	Color		Min.	Тур.	Max.	Max.	Min.	Тур.	Max.	Min.	Тур. Мах		x. 7	Тур.	
			I _F =20mA			V _R =5V	I _F =20mA								
OSWA1204C1E	White	WA		2.8	-	3.4	10	300	450		8200K	10500	K	12500K	120
OSM51204C1E	Warm White	M5		2.8	-	3.4	10	300	450		2700K	29001	K	3300K	120
OSK41204C1E	Pink	K4		2.8		3.4	10	100	200			X:0.22 Y:0.08			120
OSB51204C1E	Blue	B5		2.8	-	3.4	10	120	210		462	467		472	120
OSG51204C1E	True Green	G5		2.8	-	3.4	10	350	600		518	522		526	120
OSG81204C1E	Yellow Green	G8		1.8	-	2.4	10	25	50		566	569		572	120
OSY51204C1E	Yellow	Y5		1.8	-	2.4	10	70	150		586	589		592	120
OSO51204C1E	Orange	O5		1.8	-	2.4	10	70	150		600	605		610	120
OSR51204C1E	Red	R5		1.8	-	2.4	10	70	150		617	621		625	120

^{*1} Tolerance of measurements of chromaticity coordinate is ±10%

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^{*}Pulse width Max 0.1ms, Duty ratio max 1/10

^{*2} Tolerance of measurements of dominant wavelength is ±1nm

^{*3} Tolerance of measurements of luminous intensity is ±15%

^{*4} Tolerance of measurements of forward voltage is ±0.1V



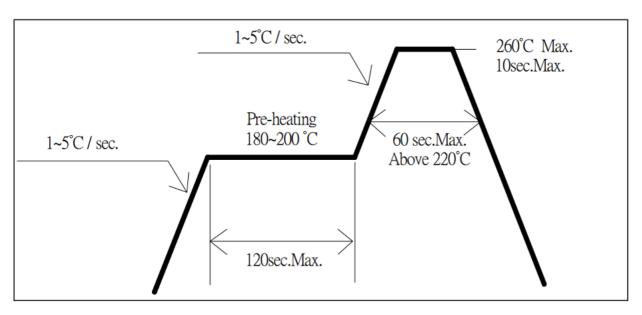
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■ Soldering Conditions

	Reflow Soldering	Hand Soldering			
Pre-Heat	180 ~ 200°C				
Pre-Heat Time	120 sec. Max.				
Peak temperature	260°C Max.	Temperature	350°C Max.		
Dipping Time	10 sec. Max.	Soldering time	3 sec. Max.		
Condition	Refer to Temperature-profile		(one time only)		

• Reflow Soldering Condition(Lead-free Solder)



- *Recommended soldering conditions vary according to the type of LED
- *Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.
- *A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- •All SMD LED products are pb-free soldering available.
- Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.







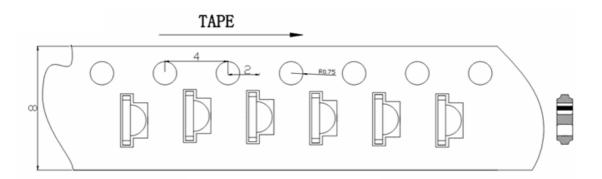


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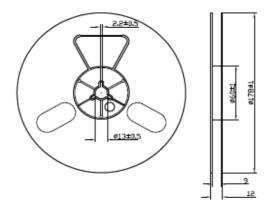
TAPING



■ Reel Dimensions

Notes:

- 1. Unit: mm
- 2. 3000pcs/Reel



■ Cautions:

- 1. After open the package, the LED's floor life is 4 Weeks under 30℃ or less and 60%RH or less(MSL:2a).
- 2. Heat generation must be taken into design consideration when using the LED.
- 3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
- 4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
- 5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
- 6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
- 7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.

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